

N-channel enhancement mode vertical D-MOS transistor

BSP122

FEATURES

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

DESCRIPTION

N-channel enhancement mode vertical D-MOS transistor in a SOT223 envelope and intended for use as a line current interruptor in telephone sets and for applications in relay, high-speed and line transformer drivers.

PINNING

PIN	DESCRIPTION
1	gate
2	drain
3	source
4	drain

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{DS}	drain-source voltage	200	V
I_D	DC drain current	550	mA
$R_{DS(on)}$	drain-source on-resistance	2.5	Ω
$V_{GS(th)}$	gate-source threshold voltage	2	V

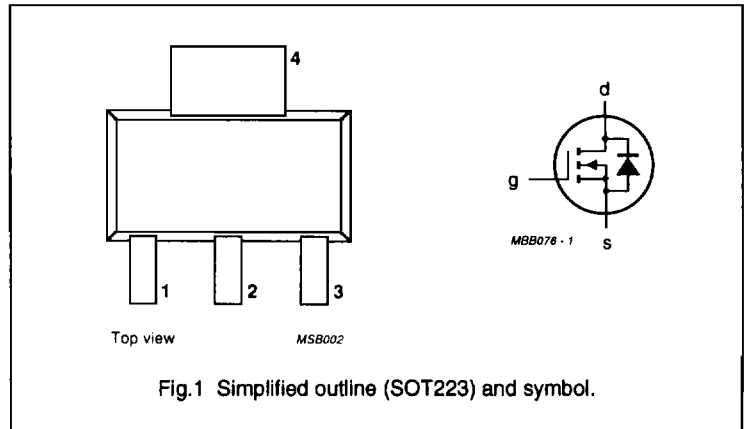


Fig.1 Simplified outline (SOT223) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage		-	200	V
$\pm V_{GSO}$	gate-source voltage	open drain	-	20	V
I_D	DC drain current		-	550	mA
I_{DM}	peak drain current		-	3	A
P_{tot}	total power dissipation	up to $T_{amb} = 25^\circ\text{C}$ (note 1)	-	1.5	W
T_{stg}	storage temperature range		-65	150	$^\circ\text{C}$
T_j	junction temperature		-	150	$^\circ\text{C}$

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
$R_{th\ j-a}$	from junction to ambient (note 1)	83.3 K/W

Note

1. Device mounted on an epoxy printed circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm².

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CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 10\text{ }\mu\text{A}; V_{GS} = 0$	200	–	–	V
I_{DSS}	drain-source leakage current	$V_{DS} = 160\text{ V}; V_{GS} = 0$	–	–	1	μA
$\pm I_{GSS}$	gate-source leakage current	$\pm V_{GS} = 20\text{ V}; V_{DS} = 0$	–	–	100	nA
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}; V_{GS} = V_{DS}$	0.4	–	2	V
$R_{DS(on)}$	drain-source on-resistance	$I_D = 750\text{ mA}; V_{GS} = 10\text{ V}$	–	1.6	2.5	Ω
		$I_D = 20\text{ mA}; V_{GS} = 2.4\text{ V}$	–	2.5	–	Ω
$ Y_{fs} $	transfer admittance	$I_D = 750\text{ mA}; V_{DS} = 25\text{ V}$	400	800	–	mS
C_{iss}	input capacitance	$V_{DS} = 25\text{ V}; V_{GS} = 0;$ $f = 1\text{ MHz}$	–	165	–	pF
C_{oss}	output capacitance	$V_{DS} = 25\text{ V}; V_{GS} = 0;$ $f = 1\text{ MHz}$	–	40	–	pF
C_{rss}	feedback capacitance	$V_{DS} = 25\text{ V}; V_{GS} = 0;$ $f = 1\text{ MHz}$	–	9	–	pF
Switching times (see Figs 2 and 3)						
t_{on}	turn-on time	$I_D = 750\text{ mA}; V_{DD} = 50\text{ V};$ $V_{GS} = 0\text{ to }10\text{ V}$	–	–	35	ns
t_{off}	turn-off time	$I_D = 750\text{ mA}; V_{DD} = 50\text{ V};$ $V_{GS} = 0\text{ to }10\text{ V}$	–	–	50	ns

